PRODUCTS AFFECTED:
XRT86VX38IB329-F
XRT86VX38IB256-F

CHANGE CATEGORY:
- Material
- Design
- Datasheet

DESCRIPTION OF CHANGE:
1. Qualified copper wire bonding assembly in addition to currently qualified gold wire bonding assembly in UTAC, China.
2. Changed die revision from A to B that includes bond pad changes for copper bond wires [Revision ID value in register 0x01FF is changed to 0x02].

IMPACT OF CHANGE:
There is no change to product form, fit or function. There is a change to the value of Rev ID register.

TARGET IMPLEMENTATION DATE: 20-FEBRUARY-2014

Please contact customer support (customersupport@exar.com) for sample date availability or qualification data.